250 mW SOT-23 Surface Mount

BZX84CxxxET1G Series, SZBZX84CxxxET1G Series

This series of Zener diodes is offered in the convenient, surface mount plastic SOT-23 package. These devices are designed to provide voltage regulation with minimum space requirement. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

Specification Features

- 250 mW Rating on FR-4 or FR-5 Board
- Zener Breakdown Voltage Range 2.4 V to 75 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Peak Power 225 W (8 X 20 μs)
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

CASE: Void-free, transfer-molded, thermosetting plastic case **FINISH:** Corrosion resistant finish, easily solderable

MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES: 260°C for 10 Seconds

POLARITY: Cathode indicated by polarity band **FLAMMABILITY RATING:** UL 94 V–0

MAXIMUM RATINGS

| Rating | Symbol | Max | Unit |
|--|------------------------------------|-------------------|---------------------|
| Peak Power Dissipation @ 20 μ s (Note 1) @ T _L \leq 25°C | P _{pk} | 225 | W |
| Total Power Dissipation on FR–5 Board, (Note 2) @ T _A = 25°C Derated above 25°C Thermal Resistance, Junction–to–Ambient | P _D R _{θJA} | 250 2.0 500 | mW mW/°C °C/W |
| Total Power Dissipation on Alumina Substrate, (Note 3) @ T _A = 25°C Derated above 25°C Thermal Resistance, Junction-to-Ambient | P _D R _{θJA} | 300 2.4 417 | mW mW/°C °C/W |
| Junction and Storage Temperature Range | T _J , T _{stg} | –65 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Nonrepetitive current pulse per Figure 9.

2. FR-5 = 1.0 X 0.75 X 0.62 in.

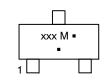
3. Alumina = 0.4 X 0.3 X 0.024 in, 99.5% alumina.



SOT-23 CASE 318 STYLE 8



MARKING DIAGRAM





 (Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-----------------|---------------------|-------------------------|
| BZX84CxxxET1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| SZBZX84CxxxET1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| BZX84CxxxET3G | SOT-23 (Pb-Free) | 10,000 / Tape & Reel |
| SZBZX84CxxxET3G | SOT-23 (Pb-Free) | 10,000 / Tape & Reel |

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 2.

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

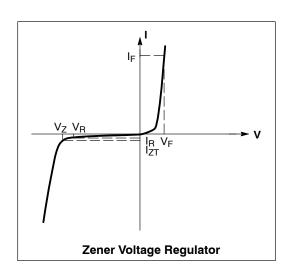
DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) (T_A = 25°C unless otherwise noted, V_F = 0.90 V Max. @ I_F = 10 mA)

| Symbol | Parameter |
|-----------------|--|
| VZ | Reverse Zener Voltage @ I _{ZT} |
| I _{ZT} | Reverse Current |
| Z _{ZT} | Maximum Zener Impedance @ I _{ZT} |
| I _R | Reverse Leakage Current @ V _R |
| V _R | Reverse Voltage |
| ١ _F | Forward Current |
| V _F | Forward Voltage @ I _F |
| ΘV_Z | Maximum Temperature Coefficient of V_Z |
| С | Max. Capacitance @ $V_R = 0$ and f = 1 MHz |



ELECTRICAL CHARACTERISTICS

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) (T_A = 25°C unless otherwise noted, V_F = 0.90 V Max. @ I_F = 10 mA)

| | | | V _{Z1} (V) _{ZT1} = 5 (Note 4) | mA | Z _{ZT1} (Ω) @ I _{ZT1} | @ I _{ZT} m | - | Z _{ZT2} (Ω) @ I _{ZT2} | V _{Z3} @ I _{ZT3} : / (Not | =20 m- \ | Z _{ZT3} (Ω) @ | Rev Leal | ax erse kage rent | θ\ (m\ (I _{ZT1} = | //k) 9 | C (pF) @ V _B = 0 |
|---------------|-------------------|-----|---|-----|---|------------------------|-----|---|--|-------------|------------------------------|------------------------|----------------------------|--------------------------------------|-----------|-----------------------------------|
| Device* | Device Marking | Min | Nom | Max | = 5 mA | Min | Max | = 1 mA | Min | Max | I _{ZT3} = 20 mA | Ι _R μΑ @ | ₽ V _R (V) | Min | Max | f = 1 MHz |
| BZX84C2V4ET1G | BA1 | 2.2 | 2.4 | 2.6 | 100 | 1.7 | 2.1 | 600 | 2.6 | 3.2 | 50 | 50 | 1.0 | -3.5 | 0 | 450 |
| BZX84C6V2ET1G | BB3 | 5.8 | 6.2 | 6.6 | 10 | 5.6 | 6.6 | 150 | 5.8 | 6.8 | 6 | 3.0 | 4.0 | 0.4 | 3.7 | 185 |

DISCONTINUED (Note 5)

| | T | 1 | | 1 | | r | r | | r | 1 | | 1 | 1 | 1 | | |
|---------------|-----|------|-----|------|-----|------|------|-----|------|------|----|------|------|------|------|-----|
| BZX84C2V7ET1G | BA2 | 2.5 | 2.7 | 2.9 | 100 | 1.9 | 2.4 | 600 | 3.0 | 3.6 | 50 | 20 | 1.0 | -3.5 | 0 | 450 |
| BZX84C13ET1G | BC2 | 12.4 | 13 | 14.1 | 30 | 12.3 | 14 | 170 | 12.5 | 14.2 | 15 | 0.1 | 8.0 | 7.0 | 11 | 120 |
| BZX84C16ET1G | BC4 | 15.3 | 16 | 17.1 | 40 | 15.2 | 17 | 200 | 15.4 | 17.2 | 20 | 0.05 | 11.2 | 10.4 | 14 | 105 |
| BZX84C22ET1G | BC7 | 20.8 | 22 | 23.3 | 55 | 20.7 | 23.2 | 250 | 20.9 | 23.4 | 25 | 0.05 | 15.4 | 16.4 | 20 | 85 |
| BZX84C10ET1G | BB8 | 9.4 | 10 | 10.6 | 20 | 9.3 | 10.6 | 150 | 9.4 | 10.7 | 10 | 0.2 | 7.0 | 4.5 | 8.0 | 130 |
| BZX84C7V5ET1G | BB5 | 7.0 | 7.5 | 7.9 | 15 | 6.9 | 7.9 | 80 | 7.0 | 8.0 | 6 | 1.0 | 5.0 | 2.5 | 5.3 | 140 |
| BZX84C5V1ET1G | BB1 | 4.8 | 5.1 | 5.4 | 60 | 4.2 | 5.3 | 480 | 5.0 | 5.9 | 15 | 2.0 | 2.0 | -2.7 | 1.2 | 225 |
| BZX84C4V3ET1G | BA7 | 4.0 | 4.3 | 4.6 | 90 | 3.3 | 4.0 | 600 | 4.4 | 5.1 | 30 | 3.0 | 1.0 | -3.5 | 0 | 450 |
| BZX84C6V8ET1G | BB4 | 6.4 | 6.8 | 7.2 | 15 | 6.3 | 7.2 | 80 | 6.4 | 7.4 | 6 | 2.0 | 4.0 | 1.2 | 4.5 | 155 |
| BZX84C3V3ET1G | BA4 | 3.1 | 3.3 | 3.5 | 95 | 2.3 | 2.9 | 600 | 3.6 | 4.2 | 40 | 5.0 | 1.0 | -3.5 | 0 | 450 |
| BZX84C18ET1G | BC5 | 16.8 | 18 | 19.1 | 45 | 16.7 | 19 | 225 | 16.9 | 19.2 | 20 | 0.05 | 12.6 | 12.4 | 16 | 100 |
| BZX84C5V6ET1G | BB2 | 5.2 | 5.6 | 6.0 | 40 | 4.8 | 6.0 | 400 | 5.2 | 6.3 | 10 | 1.0 | 2.0 | -2 | 2.5 | 200 |
| BZX84C3V0ET1G | BA3 | 2.8 | 3.0 | 3.2 | 95 | 2.1 | 2.7 | 600 | 3.3 | 3.9 | 50 | 10 | 1.0 | -3.5 | 0 | 450 |
| BZX84C8V2ET1G | BB6 | 7.7 | 8.2 | 8.7 | 15 | 7.6 | 8.7 | 80 | 7.7 | 8.8 | 6 | 0.7 | 5.0 | 3.2 | 6.2 | 135 |
| BZX84C15ET1G | BC3 | 13.8 | 15 | 15.6 | 30 | 13.7 | 15.5 | 200 | 13.9 | 15.7 | 20 | 0.05 | 10.5 | 9.2 | 13 | 110 |
| BZX84C11ET1G | BB9 | 10.4 | 11 | 11.6 | 20 | 10.2 | 11.6 | 150 | 10.4 | 11.8 | 10 | 0.1 | 8.0 | 5.4 | 9.0 | 130 |
| BZX84C20ET1G | BC6 | 18.8 | 20 | 21.2 | 55 | 18.7 | 21.1 | 225 | 18.9 | 21.4 | 20 | 0.05 | 14 | 14.4 | 18 | 85 |
| BZX84C24ET1G | BC8 | 22.8 | 24 | 25.6 | 70 | 22.7 | 25.5 | 250 | 22.9 | 25.7 | 25 | 0.05 | 16.8 | 18.4 | 22 | 80 |
| BZX84C3V6ET1G | BA5 | 3.4 | 3.6 | 3.8 | 90 | 2.7 | 3.3 | 600 | 3.9 | 4.5 | 40 | 5.0 | 1.0 | -3.5 | 0 | 450 |
| BZX84C4V7ET1G | BA9 | 4.4 | 4.7 | 5.0 | 80 | 3.7 | 4.7 | 500 | 4.5 | 5.4 | 15 | 3.0 | 2.0 | -3.5 | 0.2 | 260 |
| BZX84C9V1ET1G | BB7 | 8.5 | 9.1 | 9.6 | 15 | 8.4 | 9.6 | 100 | 8.5 | 9.7 | 8 | 0.5 | 6.0 | 3.8 | 7.0 | 130 |
| BZX84C3V9ET1G | BA6 | 3.7 | 3.9 | 4.1 | 90 | 2.9 | 3.5 | 600 | 4.1 | 4.7 | 30 | 3.0 | 1.0 | -3.5 | -2.5 | 450 |



BZX84CxxxET1G Series, SZBZX84CxxxET1G Series

ELECTRICAL CHARACTERISTICS

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) ($T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 0.90$ V Max. @ $I_F = 10$ mA)

| | | | _{Z1} Belo _{ZT1} = 2 | | Z _{ZT1} Below @ I _{ZT1} | | Below T2 = mA | Z _{ZT2} Below @ I _{ZT4} | | Below = 10 m- A | Z _{ZT3} Below @ I _{ZT3} | | | θ _\ (m\ Bel @ I _{ZT} m | low ₁ = 2 | C (pF) @ V _R = |
|--------------|-------------------|-----|--|-----|---|------|---------------------|---|------|-----------------------|---|------------------------|-------------------------|--|-------------------------|------------------------------|
| Device* | Device Marking | Min | Nom | Max | = 2 mA | Min | Max | = 0.5 mA | Min | Max | = 10 mA | Ι _R μΑ @ |) V _R (V) | Min | Max | f = 1 MHz |
| BZX84C30ET1G | BD1 | 28 | 30 | 32 | 80 | 27.8 | 32 | 300 | 28.1 | 32.4 | 50 | 0.05 | 21 | 24.4 | 29.4 | 70 |

DISCONTINUED (Note 5)

| BZX84C47ET1G | BD5 | 44 | 47 | 50 | 170 | 43.7 | 50 | 375 | 44.1 | 50.5 | 90 | 0.05 | 32.9 | 42 | 51.8 | 40 |
|--------------|-----|------|----|------|-----|------|------|-----|------|------|-----|------|------|------|------|-----|
| BZX84C56ET1G | BD7 | 52 | 56 | 60 | 200 | 51.5 | 60 | 425 | 52.1 | 60.8 | 110 | 0.05 | 39.2 | 52.2 | 63.8 | 40 |
| BZX84C62ET1G | BD8 | 58 | 62 | 66 | 215 | 57.4 | 66 | 450 | 58.2 | 67 | 120 | 0.05 | 43.4 | 58.8 | 71.6 | 35 |
| BZX84C43ET1G | BK6 | 40 | 43 | 46 | 150 | 39.7 | 46 | 375 | 40.1 | 46.5 | 80 | 0.05 | 30.1 | 37.6 | 46.6 | 40 |
| BZX84C36ET1G | BD3 | 34 | 36 | 38 | 90 | 33.8 | 38 | 350 | 34.1 | 38.4 | 60 | 0.05 | 25.2 | 30.4 | 37.4 | 70 |
| BZX84C27ET1G | BC9 | 25.1 | 27 | 28.9 | 80 | 25 | 28.9 | 300 | 25.2 | 29.3 | 45 | 0.05 | 18.9 | 21.4 | 25.3 | 70 |
| BZX84C39ET1G | BD4 | 37 | 39 | 41 | 130 | 36.7 | 41 | 350 | 37.1 | 41.5 | 70 | 0.05 | 27.3 | 33.4 | 41.2 | 45 |
| BZX84C33ET1G | BD2 | 31 | 33 | 35 | 80 | 30.8 | 35 | 325 | 31.1 | 35.4 | 55 | 0.05 | 23.1 | 27.4 | 33.4 | 70 |
| BZX84C12ET1G | BC1 | 11.4 | 12 | 12.7 | 25 | 11.2 | 12.7 | 150 | 11.4 | 12.9 | 10 | 0.1 | 8.0 | 6.0 | 10 | 130 |
| BZX84C51ET1G | BD6 | 48 | 51 | 54 | 180 | 47.6 | 54 | 400 | 48.1 | 54.6 | 100 | 0.05 | 35.7 | 46.6 | 57.2 | 40 |
| BZX84C75ET1G | BE1 | 70 | 75 | 79 | 255 | 69.4 | 79 | 500 | 70.3 | 80.2 | 140 | 0.05 | 52.5 | 73.4 | 88.6 | 35 |
| BZX84C68ET1G | BD9 | 64 | 68 | 72 | 240 | 63.4 | 72 | 475 | 64.2 | 73.2 | 130 | 0.05 | 47.6 | 65.6 | 79.8 | 35 |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

* Include SZ-prefix devices where applicable.

4. Zener voltage is measured with a pulse test current I_Z at an ambient temperature of 25°C

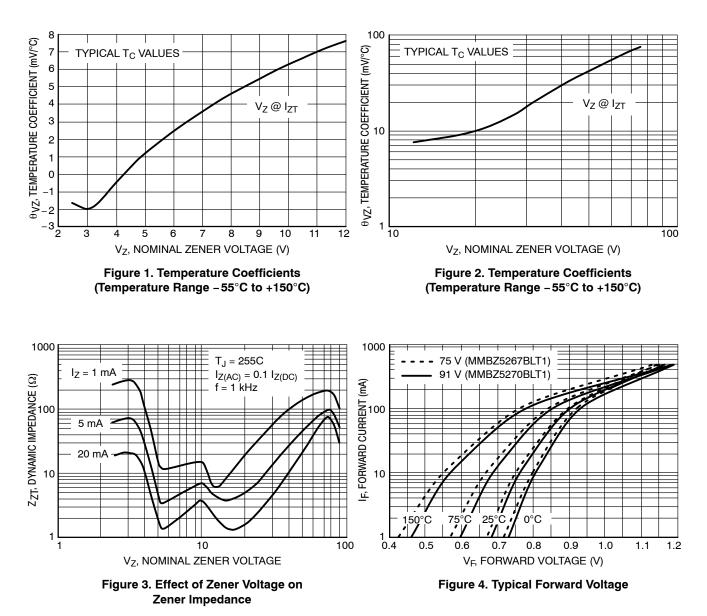
5. DISCONTINUED: These devices are not recommended for new design. Please contact your onsemi representative for information. The most current information on these devices may be available on www.onsemi.com.





BZX84CxxxET1G Series, SZBZX84CxxxET1G Series

TYPICAL CHARACTERISTICS

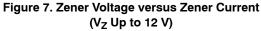


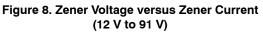


BZX84CxxxET1G Series, SZBZX84CxxxET1G Series

1000 1000 $T_A = 25^{\circ}C$ 0 V BIAS 1 V BIAS C, CAPACITANCE (pF) 11 12 +150°C **BIAS AT** 50% OF V7 NOM +25°C 0.001 55°C 0.0001 1 .00001 100 10 30 40 90 10 0 20 50 60 70 80 1 VZ, NOMINAL ZENER VOLTAGE (V) V₇, NOMINAL ZENER VOLTAGE (V) Figure 5. Typical Capacitance Figure 6. Typical Leakage Current 100 100 $T_A = 25^{\circ}C$ $T_A = 25^{\circ}C$ ZENER CURRENT (mA) ZENER CURRENT (mA) 10 10 1 1 Ń 0.1 0.01 0.01 30 50 70 90 2 8 10 12 10 Λ 4 6 V_Z, ZENER VOLTAGE (V) V_Z, ZENER VOLTAGE (V)







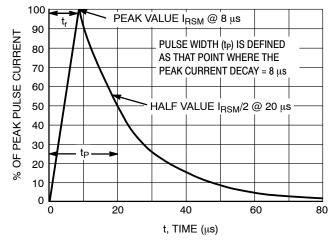


Figure 9. 8 \times 20 μs Pulse Waveform



semi



SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318**

ISSUE AU

DATE 14 AUG 2024













XXX = Specific Device Code М = Date Code

= Pb-Free Package .

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



| | MILLIMETERS | | | | | | | | | | |
|-----|-------------|------|------|--|--|--|--|--|--|--|--|
| DIM | MIN | NOM | МАХ | | | | | | | | |
| А | 0.89 | 1.00 | 1.11 | | | | | | | | |
| A1 | 0.01 | 0.06 | 0.10 | | | | | | | | |
| b | 0.37 | 0.44 | 0.50 | | | | | | | | |
| с | 0.08 | 0.14 | 0.20 | | | | | | | | |
| D | 2.80 | 2.90 | 3.04 | | | | | | | | |
| E | 1.20 | 1.30 | 1.40 | | | | | | | | |
| е | 1.78 | 1.90 | 2.04 | | | | | | | | |
| L | 0.30 | 0.43 | 0.55 | | | | | | | | |
| L1 | 0.35 | 0.54 | 0.69 | | | | | | | | |
| Ηe | 2.10 | 2.40 | 2.64 | | | | | | | | |
| Т | 0° | | 10° | | | | | | | | |

NOTES:

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS: 1.

2. MILLIMETERS.

MILLIME IERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE 3.

BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, 4. PROTRUSIONS, OR GATE BURRS.

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CÁSE 318** ISSUE AU

DATE 14 AUG 2024

| STYLE 1 THRU 5: CANCELLED | STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR | STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR | STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE | I | |
|---|---|---|--|------------------|------------------|
| STYLE 9: | STYLE 10: | STYLE 11: | STYLE 12: | STYLE 13: | STYLE 14: |
| PIN 1. ANODE | PIN 1. DRAIN | PIN 1. ANODE | PIN 1. CATHODE | PIN 1. SOURCE | PIN 1. CATHODE |
| 2. ANODE | 2. SOURCE | 2. CATHODE | 2. CATHODE | 2. DRAIN | 2. GATE |
| 3. CATHODE | 3. GATE | 3. CATHODE-ANODE | 3. ANODE | 3. GATE | 3. ANODE |
| STYLE 15: | STYLE 16: | STYLE 17: | STYLE 18: | STYLE 19: | STYLE 20: |
| PIN 1. GATE | PIN 1. ANODE | PIN 1. NO CONNECTION | PIN 1. NO CONNECTION | I PIN 1. CATHODE | PIN 1. CATHODE |
| 2. CATHODE | 2. CATHODE | 2. ANODE | 2. CATHODE | 2. ANODE | 2. ANODE |
| 3. ANODE | 3. CATHODE | 3. CATHODE | 3. ANODE | 3. CATHODE-ANODE | 3. GATE |
| STYLE 21: | STYLE 22: | STYLE 23: | STYLE 24: | STYLE 25: | STYLE 26: |
| PIN 1. GATE | PIN 1. RETURN | PIN 1. ANODE | PIN 1. GATE | PIN 1. ANODE | PIN 1. CATHODE |
| 2. SOURCE | 2. OUTPUT | 2. ANODE | 2. DRAIN | 2. CATHODE | 2. ANODE |
| 3. DRAIN | 3. INPUT | 3. CATHODE | 3. SOURCE | 3. GATE | 3. NO CONNECTION |
| STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE | STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE | | | | |

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